Product/Process Change Notice - PCN 11_0046 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: SSM2375 Alternate Manufacturing Site for Wafer Fab

Publication Date: 07-Apr-2011

Effectivity Date: 06-Jul-2011 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

Adding additional wafer fab manufacturing capacity at MagnaChip - Korea.
SSM2375 is currently manufactured at wafer fab, TSMC Fab11,USA

Reason For Change

Increase wafer fabrication capacity.

Impact of the change (positive or negative) on fit, form, function & reliability

No expected change to Product Fit, Form, Function or Reliability

Product Identification *(this section will describe how to identify the changed material)*

Processing location traceable by lot and datecode and Country of Diffusion on the shipment label.

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Plan Summary

ADI_PCN_11_0046_Rev_-_SSM2375_Qual Plan.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative					
Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models	
Added Parts On This Revision - Product Family / Model Number (2)	
SSM2375 / SSM2375CBZ-REEL	SSM2375 / SSM2375CBZ-REEL7

Appendix B - Revision History		
Rev	**Publish Date**	**Rev Description**
Rev. -	07-Apr-2011	Initial Release